

Variant: None
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 TID #: TIDA-01506



TIDA-01506 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		TIDA-01506	Any	Printed Circuit Board	
2	C1, C7, C8	3	0.1uF	0603YC104JAT2A	AVX	CAP, CERM, 0.1 μ F, 16 V, +/- 5%, X7R, 0603	0603
3	C2, C5, C9, C10, C11	5	1uF	CGA3E1X7R1V105K080AC	TDK	CAP, CERM, 1 μ F, 35 V, +/- 10%, X7R, AEC-Q200 Grade 1, 0603	0603
4	C3, C6	2	0.1uF	GRM188R72A104KA35J	MuRata	CAP, CERM, 0.1 μ F, 100 V, +/- 10%, X7R, 0603	0603
5	C4	1	2.2uF	GRM188Z71C225KE43	MuRata	CAP, CERM, 2.2 μ F, 16 V, +/- 10%, X7R, 0603	0603
6	D1	1	40V	B540C-13-F	Diodes Inc.	Diode, Schottky, 40 V, 5 A, SMC	SMC
7	D2	1	20V	SM4T23AY	STMicroelectronics	Diode, TVS, Uni, 20 V, 42.8 Vc, AEC-Q101, SMA	SMA
8	D3	1	20V	B120-13-F	Diodes Inc.	Diode, Schottky, 20 V, 1 A, SMA	SMA
9	J1	1		0022284043	Molex	Header, 2.54mm, 4x1, Tin, TH	Header, 2.54mm, 4x1, TH
10	J2, J3	2		39357-0002	Molex	Terminal Block, 3.5 mm, 2x1, Tin, TH	Terminal Block, 3.5 mm, 2x1, TH
11	R1	1	50	FC0603E50R0BTBST1	Vishay Thin Film	RES, 50, 0.1%, 0.125 W, 0603	0603
12	R2	1	0.1	UR73V2BTTDR100F	KOA Speer	RES, 0.1, 1%, 0.5 W, AEC-Q200 Grade 1, 1206	1206
13	R3, R5, R6	3	10k	CRCW060310K0JNEA	Vishay-Dale	RES, 10 k, 5%, 0.1 W, 0603	0603
14	R4	1	750	CRCW0805750RJNEA	Vishay-Dale	RES, 750, 5%, 0.125 W, 0805	0805
15	R7	1	1.00k	CRCW08051K00FKEA	Vishay-Dale	RES, 1.00 k, 1%, 0.125 W, 0805	0805
16	U1	1		TPS70950QDBVRQ1	Texas Instruments	150-mA, 30-V, Ultra-Low IQ, Wide Input LDO with Reverse Current Protection for Automotive, DBV0005A (SOT-23-5)	DBV0005A
17	U2	1		INA240A1QPWRQ1	Texas Instruments	Automotive, Wide Common-Mode Range, High- and Low-Side, Bidirectional, Zero-Drift, Current-Sense Amplifier With Enhanced PWM Rejection, PW0008A (TSSOP-8)	PW0008A
18	U3	1		TPS1H100AQPWRQ1	Texas Instruments	40V/100mOhm Single Channel Smart High Side Switch, PWP0014F (TSSOP-14)	PWP0014F

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